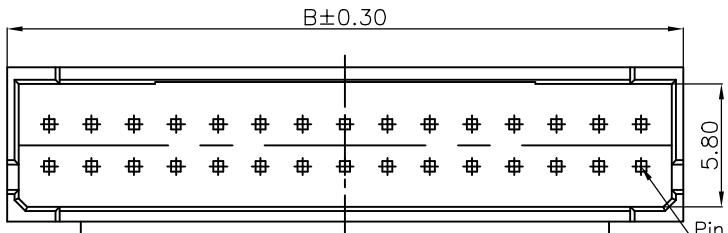
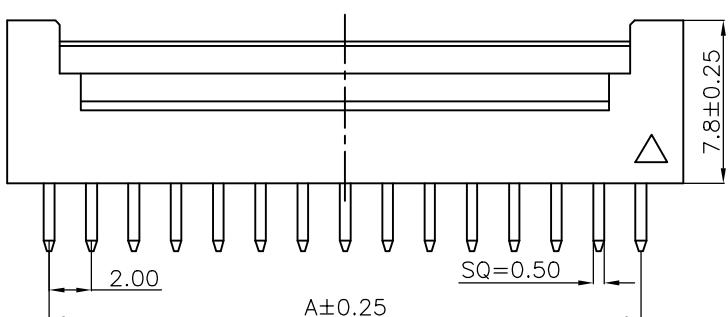


ROHS G591

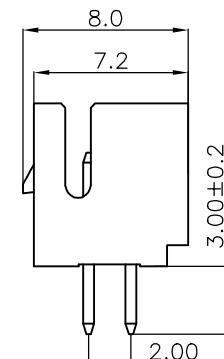
A



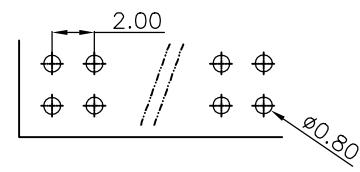
B



C



D

RECOMMENDED PCB LAYOUT  
(TOLERANCE: ±0.10)

E

F

G

H

## 1.ELECTRICAL SPECIFICATIONS:

- 1.1 Rated current and voltage(额定电流): 3.0A 250V AC(r.m.s)
- 1.2 Dielectric Withstanding Voltage(耐电压) : 800V AC for one minute
- 1.3 Contact Resistance(接触电阻) : 20mΩ max
- 1.4 Insulation Resistance(绝缘电阻) : 1000MΩ min
- 1.5 Operating Temperature(工作温度) : -25°C ~ 85°C

## 2.MATERIAL SPECIFICATION:

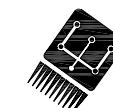
- 2.1 Insulator Material(绝缘体材质): PA46 UL94V-0
- 2.2 Contact Material(端子材质): Brass,Tin Plated

PART NO. LEGEND:  
WB2013DS-XXT3C-P

Insulator Material: 3:PA46
Contact Plating :T:Tin all Over
NO of Contacts: 4 to 40
Welding Method:DS=DIP180°
Wafer Conn

▲ Non-tooled parts  
No.of positions DIM list:

CONTACTS	DIMENSIONS	
	A	B
4	2.00	6.00
6	4.00	8.00
8	6.00	10.00
10	8.00	12.00
12	10.00	14.00
14	12.00	16.00
16	14.00	18.00
18	16.00	20.00
20	18.00	22.00
22	20.00	24.00
24	22.00	26.00
26	24.00	28.00
28	26.00	30.00
30	28.00	32.00
32	30.00	34.00
34	32.00	36.00
36	34.00	38.00
38	36.00	40.00
40	38.00	42.00

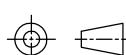


**CHIN-BAN**  
electronics (H.K.) co., Ltd

E			
D			
C			
B			
A			
NO.	DATE	DESCRIPTION	APPROVAL

DRAWING:  
Hu yatao  
CHECKED:  
Tony  
APPROVAL:  
Yang jie

GENERAL TOLERANCE  
.X:=±0.30    .X\*:=±2°  
.XX:=±0.25    .XX\*:=±1°  
.XXX:=±0.15    .XXX\*:=±0.5°  
UNIT: MM    PROJECTION:  
SCALE: N/A   



SHEET: 1/1

DESCRIPTION:  
2.00mm Wire To Board Wafer Double Row 180°  
PART NO: WB2013DS-XXT3C-P    REV: 1.0  
CUSTOMER NO:    SIZE: A4